

# WEST Search History

DATE: Tuesday, April 15, 2003

<u>Set Name</u> side by side	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u> result set
	DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=ADJ		
L24	l23 and (lid or cap or cover) and (package or packaged)	2	L24
L23	l10 and reflow	7	L23
L22	l10 and (shield or module)	0	L22
L21	l10 and (battery or cell) and (lead or terminal)	6	L21
L20	l10 and lead frame	4	L20
L19	l10 and (lid or cap or cover) and (package or packaged)	3	L19
L18	l6 and (lid or cap or cover) and (package or packaged)	53	L18
L17	l6 and (shield or module)	52	L17
L16	l6 and (battery or cell) and (lead or terminal)	31	L16
L15	l6 and battery terminal	0	L15
L14	l6 and lead frame	54	L14
L13	L10 and (sn or tin) near (ag or silver)	5	L13
L12	l10 and (invar or kovar or stainless or alloy 42 or (fe or iron) near (ni or nickel) or nitinol)	5	L12
L11	L10 and (sonic or ultrasonic)	0	L11
L10	L9 and l8	21	L10
L9	l3 and (electroless or electrolessly or electrolytic or electrolytically or electro) near (plate or plated or plating)	108	L9
L8	l3 and (solder or soldered or soldering or tin or tinned or tinning) near (dip or dipped or dipping or immerse or immersed or immersion or immersing)	32	L8
L7	L6 and (sn or tin) near (ag or silver)	29	L7
L6	l3 and ((solder or soldered or soldering or tin or tinned or tinning or plate or plated or (electroless or electrolessly or electrolytic or electrolytically or electro) near (plate or plated or plating) or plating)) near (sn or "tin" or au or gold or ag or silver or cu or copper or ni or nickel)	255	L6
L5	l3 and (invar or kovar or stainless or alloy 42 or (fe or iron) near (ni or nickel) or nitinol)	86	L5
L4	L3 and (battery or electrochemical cell) and (terminal or lead)	9	L4
L3	l2 and ((solder or soldered or soldering or tin or tinned or tinning) and (plate or plated or (electroless or electrolessly or electrolytic or electrolytically or electro) near (plate or plated or plating) or plating)) near (thick or thickness or micron or micrometer or micrometre or	324	L3

	".mu.m")		
L2	L1 and (thick or thickness or micron or micrometer or micrometre or ".mu.m")	66707	L2
L1	(substrate or die or semiconductor or wafer or chip) and (solder or soldered or soldering or tin or tinned or tinning) and (plate or plated or (electroless or electrolessly or electrolytic or electrolytically or electro) near (plate or plated or plating) or plating)	93177	L1

END OF SEARCH HISTORY